



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20230412000.1

**Qualification of CDAT as an additional Assembly site for Select Devices
Change Notification / Sample Request**

Date: April 12, 2023

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If additional data is required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20230412000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS61240DRVT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20230412000.1			PCN Date:	April 12, 2023												
Title:	Qualification of CDAT as an alternate Assembly site for select devices																
Customer Contact:	PCN Manager	Dept:	Quality Services														
Proposed 1st Ship Date:	Jul 11, 2023	Sample Requests accepted until:	May 12, 2023*														
*Sample requests received after May 12, 2023 will not be supported.																	
Change Type:																	
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site												
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material												
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process												
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site												
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials												
		<input type="checkbox"/>	Wafer Fab Process														
PCN Details																	
Description of Change:																	
<p>Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for set of devices listed below. Construction differences are as follows:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th></th> <th>UTL1</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>SID#CZ0141</td> <td>4222198</td> </tr> <tr> <td>Mount Compound</td> <td>SID#PZ0031</td> <td>4207123</td> </tr> <tr> <td>Bond wire composition, diameter</td> <td>Au, 1.3 mil</td> <td>Cu, 1.0 mil</td> </tr> </tbody> </table>							UTL1	CDAT	Mold Compound	SID#CZ0141	4222198	Mount Compound	SID#PZ0031	4207123	Bond wire composition, diameter	Au, 1.3 mil	Cu, 1.0 mil
	UTL1	CDAT															
Mold Compound	SID#CZ0141	4222198															
Mount Compound	SID#PZ0031	4207123															
Bond wire composition, diameter	Au, 1.3 mil	Cu, 1.0 mil															
Reason for Change:																	
Supply continuity																	
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																	
None																	
Impact on Environmental Ratings																	
<p>Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.</p> <table border="1" style="width: 100%;"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>						RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change				
RoHS	REACH	Green Status	IEC 62474														
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change														
Changes to product identification resulting from this PCN:																	
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City														
UTL1	NSE	THA	Bangkok														
CDAT	CDA	CHN	Chengdu														
Sample product shipping label (not actual product label)																	

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 20:

G4

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CCO: USA
(22L) AS0: MLA (23L) ACO: MYS

MSL '2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750

Product Affected:

TPS61240DRVR

TPS61240DRVT



TI Information
Selective Disclosure

Qualification Report

TPS61240DRV
Approve Date 16-March-2023
Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS61240DRV	QBS Product Reference: TPS61240DRV	QBS Process Reference: UCC27524AQDGNRQ1	QBS Package Reference: SN74AXC8T24SRHL	QBS Package Reference: TVS0500DRVR
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass
HBM	ESD - HBM	2000 V	-	1/3/0	1/3/0	-	-
CDM	ESD - CDM	500 V	-	1/3/0	1/3/0	-	-
LU	Latch-up	(per JESD78)	-	1/6/0	1/6/0	-	-
HTOL	Life Test, 150C	408 Hours	-	-	3/231/0	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/2400/0	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
PD	Physical Dimensions	-	1/30/0	1/30/0	-	3/90/0	-
SD	Solderability	Pb Free	-	-	-	-	1/22/0
WBP	Bond Pull	Wires	1/30/0	1/30/0	-	3/90/0	-
WBS	Ball Bond Shear	Wires	1/30/0	1/30/0	-	3/90/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2208-002

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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